Contact Name Title - Contact Phone - Contact* Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Uniter Stewards Weight*	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company name* Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards NA NSV30100LT1G SSP LOW VCES 30V PNP XTR 2024-05-09 CN1 SSP LOW VCES 30V PNP XTR NA NSV30100LT1G SSP LOW VCES 30V PNP XTR NSV30100LT1G SSP LOW VCES 30V PNP XTR NA NSV3010LT1G SSP LOW VCES 30V PNP XTR NAMINGACTURING NAMING	752-21.1											als and M	fg Informat	ion	
Semilar Freduct Name Freduct Enviro Compliance Freduct Enviro Enviro Enviro Stewards@onsemi.com Freduct Enviro Enviro Stewards@onsemi.com Freduct Enviro Envir	upplier Informa	ation													
Title - Contact Name Product Envi-Stewards Product-Env-Stewards Produc	Company name* Company				npany unique ID			Unique ID Authority				Response Date*			
Product Env-Stewards Authorized Representative* Title - Representative Product Enviro Compliance NA Product Enviro Stewards @ onsemi.com Nanufacturing Site Weight* UOM Un NSV30100LT1G SSP LOW VCES 30V PNP XTR 2024-05-09 Product Enviro Compliance NA Nanufacturing Site Nanufacturing Sit	nsemi											2024-05-09			
Authorized Representative* Product Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Uniter Number Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy Title - Representative Phone - Representative* Phone - Representative* Phone - Representative* Phone - Representative* Product Env-Stewards@onsemi.com NA Product-Env-Stewards@onsemi.com Version Manufacturing Site Weight* UOM Uniter Stewards@onsemi.com Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Nater Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Requester Item Number Mfr	Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	tative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
NSV30100LT1G SSP LOW VCES 30V PNP XTR 2024-05-09 CN1 8.13 mg Each	Product-Env-Stewar	ds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date	e Version	n I	Manufacturing Site	,	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			NSV30100LT1G SSP LOW VCES 30		0V PNP XTR		2024-05-09	CN1		8	3.13	mg	Each		
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments				ampinal Daga	Allow	CTD 020 MCI	I. Dotino	Dools Duo	anna Dadu	Tomanountu	May Time at Deals	Tomamorat	numa Niversita	han of Doflaw Cw	Jac
omments				•		S I D-020 MSI	L Kaung							ber of Reflow Cyc	cies
		(SII) - anneaied		U Alloy	I			200		IC	30	secon	us [3		
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		no at neels termnerature	dunina aala	domina ia 10 3	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Lead Frame	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.5198	mg
			В	Nickel (Ni)	7440-02-0		0.9023	mg
			Supplier	Iron (Fe)	7439-89-6		1.2468	mg
			Supplier	Copper (Cu)	7440-50-8		0.2511	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg